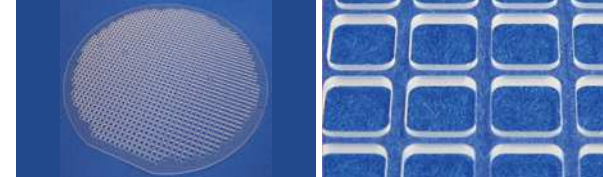


Spacer Glass

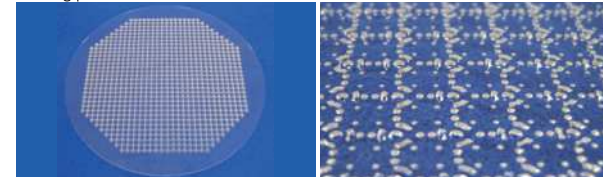
Spacer Glass

Milling process (CNC milling)



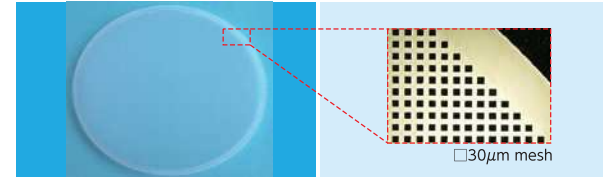
Standard specifications	
Glass material	Various glass
Hole shape	Straight
Wafer size	~φ200mm
Wafer thickness	~10mm
Dimensional tolerance	± 0.01~0.05mm
Hole size	φ0.3mm~

Blasting process



Standard specifications	
Glass material	Various glass
Hole shape	60~70° taper
Wafer size	~φ200mm
Wafer thickness	~1mm
Dimensional tolerance	± 0.01~0.05mm
Hole size	φ0.05mm~

HY process



Standard specifications	
Glass material	Various glass
Hole shape	Square
Wafer size	~φ150mm
Wafer thickness	0.1mm~
Dimensional tolerance	± 0.01mm~
Minimum shape	□30μm

Application (examples)

- Various sensors (pressure, acceleration, gyro)
- Optical device (for CMOS, CCD, LD, LED)
- Supports WLP spacer glass
- Glass filter, etc.

Option

- Minimize micro cracks that occur during processing (Minimize defect of device from particles)
- Metallization available on hole inner walls
- Metalize patterning available on glass surface
- Control sagging around holes
- Minimize chipping (Possible to 10μm)
- Control TTV

Features

- Supports various glass, hole shape, thickness
- Achieve the quality that meets your needs by adding various options

	Hole periphery comparison	Chipping comparison
Original polished product		
	Sagging area Width<10μm Depth<0.1μm	
Standard polished product		
	Sagging area Width<400μm Depth<0.7μm	

*The specs cited on this catalog are of May 2019 and may have changes at the time of your reading. For the latest specs, please contact our sales team.